

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Hui et al. Docket No.: TI-27874  
Serial No: TBD Examiner: TBD  
Filed: 10/18/01 Art Unit: TBD  
For: DIE PAD FOR INTEGRATED CIRCUITS

S. Stevens  
12-10-01  
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PRELIMINARY AMENDMENT

October 18, 2001

Assistant Commissioner for Patents

Washington, DC 20231

Dear Sir:

Please amend the above referenced application as follows:

In the Specification:

Page 1, before line 1, insert -This application claims priority under 35 USC §

119(e)(1) of provisional application numbers 60/254,567 filed 12/11/00.--